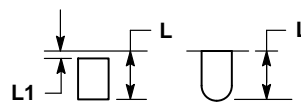
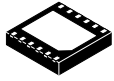
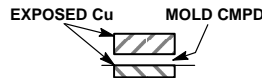


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

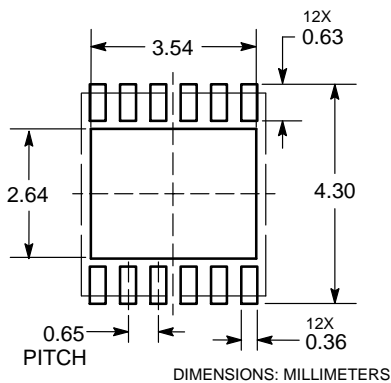
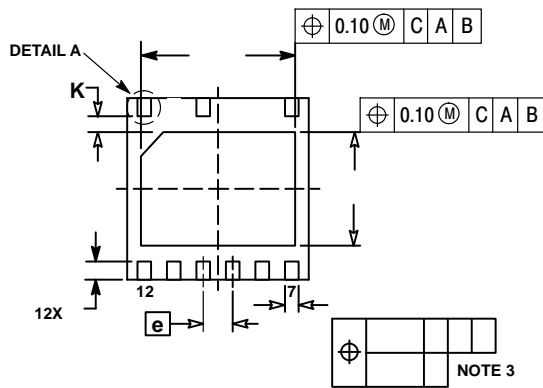
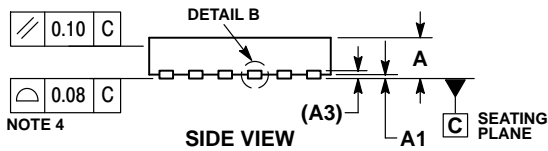


**DETAIL A**  
ALTERNATE TERMINAL  
CONSTRUCTIONS

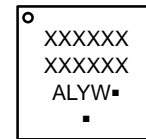


**DETAIL B**  
ALTERNATE  
CONSTRUCTION

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.25	0.35
D	4.00	BSC
D2	3.30	3.50
E	4.00	BSC
E2	2.40	2.60
e	0.65	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15



## GENERIC MARKING DIAGRAM\*



- XXXXXX= Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(\*Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.